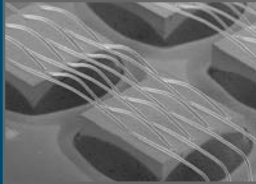
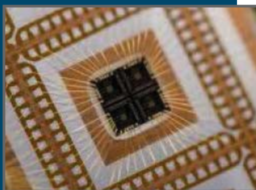
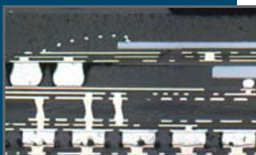
Advanced Packaging Update:

Market and Technology Trends

Vol. 4-0614







The fourth volume of the Advanced Packaging Update features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The BGA market is divided into plastic, tape, and ceramic structures. The CSP market is divided into stacked die CSPs, laminate, flex circuit, and leadframe (QFN) substrates. Package-on-package (PoP) market forecast is provided. Key applications and drivers for unit volume growth are highlighted. Trends in the conversion from gold wire to alternatives including silver, bare copper, and palladium-coated copper are described and a breakdown of the conversion in PBGAs and QFNs is provided. An economic analysis examines macroeconomic trends and their impact on the semiconductor packaging and assembly industry.

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Annual subscription – $4,200 (4 issues)
Single issue – $1,500

Contents and specifications subject to change without notice. 6/19/14